

SN74ALVC16409

9-BIT, 4-PORT UNIVERSAL BUS EXCHANGER WITH 3-STATE OUTPUTS

SCAS259A – NOVEMBER 1993 – REVISED JULY 1995

- **EPIC™ (Enhanced-Performance Implanted CMOS) Submicron Process**
- **Member of the Texas Instruments Widebus+™ Family**
- **UBE™ (Universal Bus Exchanger) Allows Synchronous Data Exchange**
- **Designed to Facilitate Incident-Wave Switching for Line Impedances of 50 Ω or Greater**
- **Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C**
- **Typical V_{OHV} (Output V_{OH} Undershoot) > 2 V at V_{CC} = 3.3 V, T_A = 25°C**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages**

**DGG OR DL PACKAGE
(TOP VIEW)**

PRE	1	56	CLK
SEL0	2	55	SELEN
1A1	3	54	1B1
GND	4	53	GND
1A2	5	52	1B2
1A3	6	51	1B3
V _{CC}	7	50	V _{CC}
1A4	8	49	1B4
1A5	9	48	1B5
1A6	10	47	1B6
GND	11	46	GND
1A7	12	45	1B7
1A8	13	44	1B8
1A9	14	43	1B9
2A1	15	42	2B1
2A2	16	41	2B2
2A3	17	40	2B3
GND	18	39	GND
2A4	19	38	2B4
2A5	20	37	2B5
2A6	21	36	2B6
V _{CC}	22	35	V _{CC}
2A7	23	34	2B7
2A8	24	33	2B8
GND	25	32	GND
2A9	26	31	2B9
SEL1	27	30	SEL4
SEL2	28	29	SEL3

description

The SN74ALVC16409 allows synchronous data exchange between four different buses.

Data flow is controlled by the select (SEL0–SEL4) inputs. A data-flow state is stored on the rising edge of the clock (CLK) input if the select-enable (SELEN) input is low. Once a data-flow state has been established, data is stored in the flip-flop on the rising edge of CLK if SELEN is high.

The data-flow control logic is designed to allow glitch-free data transmission.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVC16409 is available in TI's shrink small-outline (DL) and thin shrink small-outline (DGG) packages, which provide twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN74ALVC16409 is characterized for operation from –40°C to 85°C.



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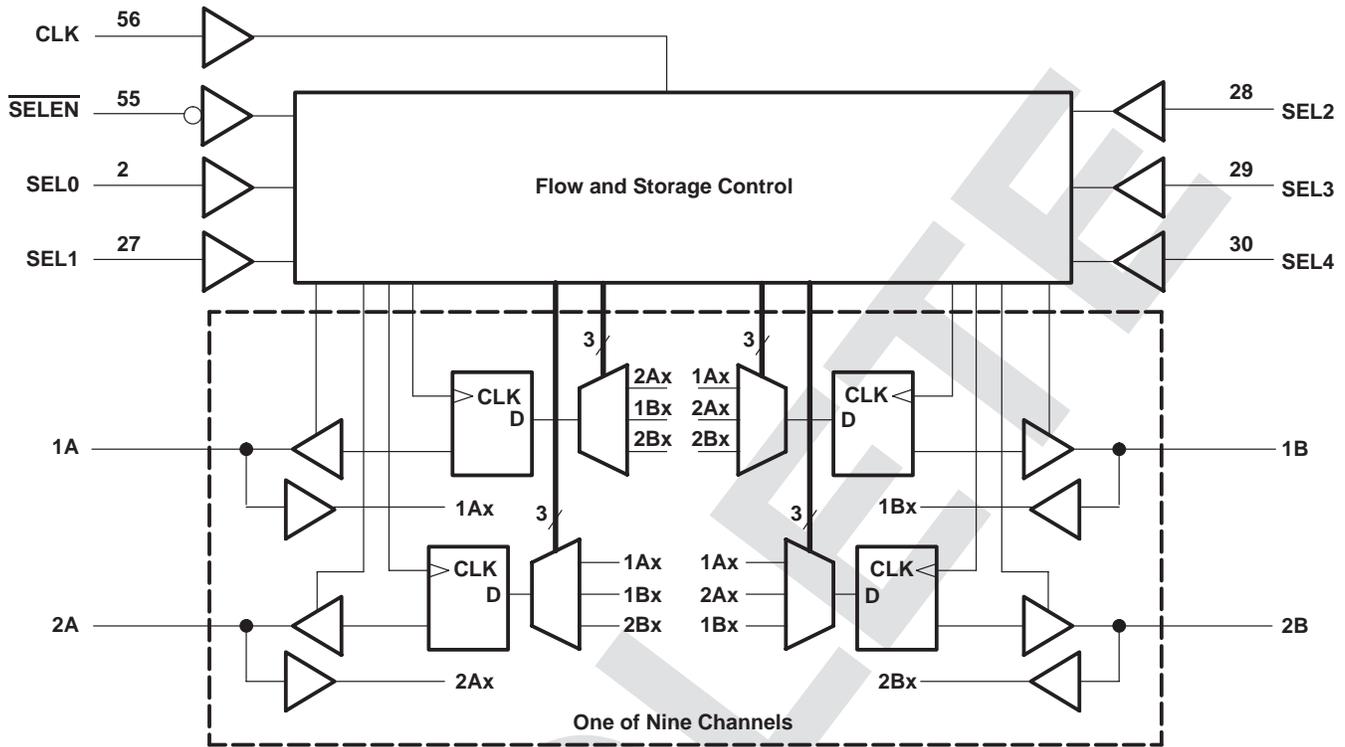
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logic diagram (positive logic)



FUNCTION TABLE

INPUTS		OUTPUT RECEIVE PORT
CLK	SEND PORT	
X	X	B_0^\dagger
X	L	L
X	H	H
↑	L	L
↑	H	H
H	X	B_0^\dagger
L	X	B_0^\dagger

† Output level before the indicated steady-state input conditions were established

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DATA-FLOW CONTROL FUNCTION TABLE

INPUTS							DATA FLOW
SELEN	CLK	SEL0	SEL1	SEL2	SEL3	SEL4	
H	↑	X	X	X	X	X	No change
L	↑	0	0	0	0	0	None, all I/Os off
L	↑	0	0	0	0	1	Not used
L	↑	0	0	0	1	0	Not used
L	↑	0	0	0	1	1	Not used
L	↑	0	0	1	0	0	Not used
L	↑	0	0	1	0	1	Not used
L	↑	0	0	1	1	0	Not used
L	↑	0	0	1	1	1	Not used
L	↑	0	1	0	0	0	2A to 1A and 1B to 2B
L	↑	0	1	0	0	1	2A to 1A
L	↑	0	1	0	1	0	2B to 1B
L	↑	0	1	0	1	1	2A to 1A and 2B to 1B
L	↑	0	1	1	0	0	1A to 2A and 1B to 2B
L	↑	0	1	1	0	1	1A to 2A
L	↑	0	1	1	1	0	1B to 2B
L	↑	0	1	1	1	1	1A to 2A and 2B to 1B
L	↑	1	0	0	0	0	1A to 1B and 2B to 2A
L	↑	1	0	0	0	1	1A to 1B
L	↑	1	0	0	1	0	2A to 2B
L	↑	1	0	0	1	1	1A to 1B and 2A to 2B
L	↑	1	0	1	0	0	1B to 1A and 2A to 2B
L	↑	1	0	1	0	1	1B to 1A
L	↑	1	0	1	1	0	2B to 2A
L	↑	1	0	1	1	1	1B to 1A and 2B to 2A
L	↑	1	1	0	0	0	2B to 1A and 2A to 1B
L	↑	1	1	0	0	1	1B to 2A
L	↑	1	1	0	1	0	2B to 1A
L	↑	1	1	0	1	1	2B to 1A and 1B to 2A
L	↑	1	1	1	0	0	1A to 2B and 1B to 2A
L	↑	1	1	1	0	1	1A to 2B
L	↑	1	1	1	1	0	2A to 1B
L	↑	1	1	1	1	1	1A to 2B and 2A to 1B



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	-0.5 V to 4.6 V
Input voltage range, V_I : Except I/O ports (see Note 1)	-0.5 V to $V_{CC} + 4.6$ V
I/O ports (see Notes 1 and 2)	-0.5 V to $V_{CC} + 0.5$ V
Output voltage range, V_O (see Notes 1 and 2)	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	-50 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V_{CC} or GND pins	±100 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 3): DGG package	1 W
DL package	1.4 W
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. This value is limited to 4.6 V maximum.
 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 4)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	2.7	3.6	V
V_{IH}	High-level input voltage	$V_{CC} = 2.7$ V to 3.6 V	2	V
		$V_{CC} = 2.3$ V to 2.7 V	1.7	
V_{IL}	Low-level input voltage	$V_{CC} = 2.7$ V to 3.6 V	0.8	V
		$V_{CC} = 2.3$ V to 2.7 V	0.7	
V_I	Input voltage	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	V
I_{OH}	High-level output current	$V_{CC} = 2.3$ V	-12	mA
		$V_{CC} = 2.7$ V	-12	
		$V_{CC} = 3$ V	-24	
I_{OL}	Low-level output current	$V_{CC} = 2.3$ V	12	mA
		$V_{CC} = 2.7$ V	12	
		$V_{CC} = 3$ V	24	
$\Delta t/\Delta v$	Input transition rise or fall rate	0	10	ns/V
T_A	Operating free-air temperature	-40	85	°C

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC} [†]	T _A = -40°C to 85°C			UNIT
			MIN	TYP [‡]	MAX	
V _{OH}	I _{OH} = -100 μA	MIN to MAX	V _{CC} - 0.2			V
	I _{OH} = -6 mA	V _{IH} = 1.7 V	2.3 V	2		
	I _{OH} = -12 mA	V _{IH} = 1.7 V	2.3 V	1.7		
		V _{IH} = 2 V	2.7 V	2.2		
	I _{OH} = -24 mA	V _{IH} = 2 V	3 V	2.4		
V _{OL}	I _{OL} = 100 μA	MIN to MAX	0.2			V
	I _{OL} = 6 mA	V _{IL} = 0.7 V	2.3 V	0.4		
	I _{OL} = 12 mA	V _{IL} = 0.7 V	2.3 V	0.7		
		V _{IL} = 0.8 V	2.7 V	0.4		
	I _{OL} = 24 mA	V _{IL} = 0.8 V	3 V	0.55		
I _I	V _I = V _{CC} or GND	3.6 V	±5			μA
I _I (hold)	V _I = 0.7 V	2.3 V	45			μA
	V _I = 1.7 V		-45			
	V _I = 0.8 V	3 V	75			
	V _I = 2 V		-75			
	V _I = 0 to 3.6 V	3.6 V	±500			
I _{OZ} [§]	V _O = V _{CC} or GND	3.6 V	±10			μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	3.6 V	40			μA
ΔI _{CC}	One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V	500			μA
C _i	V _I = V _{CC} or GND	3.3 V	4			pF
C _o	V _O = V _{CC} or GND	3.3 V	8			pF

[†] For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

[‡] All typical values are measured at V_{CC} = 3.3 V, T_A = 25°C.

[§] For I/O ports, the parameter I_{OZ} includes the input leakage current.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V	V _{CC} = 3.3 V ± 0.3 V		UNIT
		MIN	MAX	MIN	MIN	MAX	
f _{clock}	Clock frequency	0	120		0	120	MHz
t _w	Pulse duration, CLK high or low	4.2		4.2	3		ns
t _{su}	Setup time	A or B before CLK↑		1.9	1.9	1.4	ns
		S before CLK↑		5.1	4.2	3.5	
		SELEN before CLK↑		2.5	2.5	1.8	
		PRE before CLK↑		1	1	0.7	
t _h	Hold time	A or B after CLK↑		0.8	0.8	1	ns
		S after CLK↑		0	0	0	
		SELEN after CLK↑		0.5	0.5	0.8	



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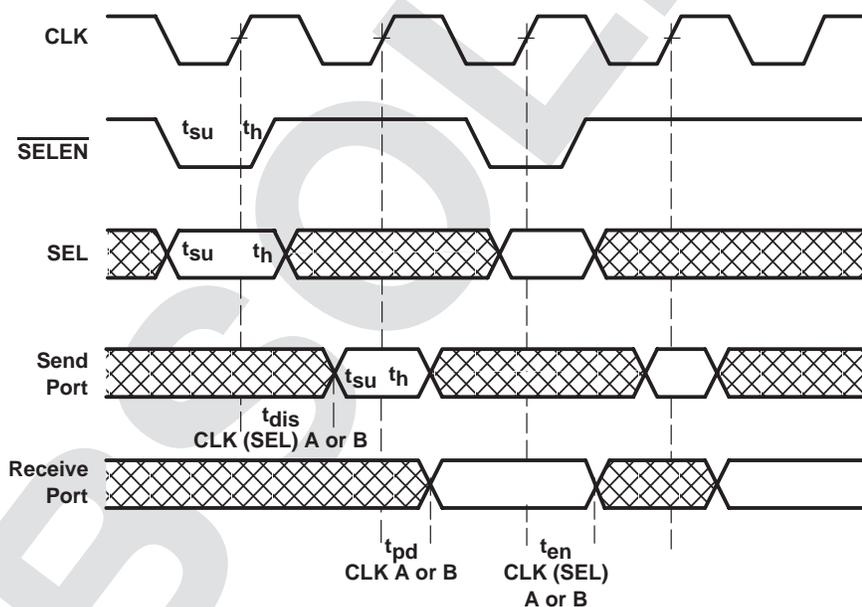
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$			$V_{CC} = 2.7\text{ V}$	$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$			UNIT
			MIN	TYP	MAX	MAX	MIN	TYP	MAX	
f_{max}			120				120			MHz
t_{pd}	CLK (A or B)	B or A	2	4.2	6.6	5.7	1.5	3.3	5.1	ns
t_{en}	CLK (SEL)	A or B	2.5	4.8	7.4	6.3	2	3.8	5.7	ns
t_{dis}	CLK (SEL)	A or B	3	5.1	7.3	6	2	4	5.7	ns
t_{dis}	\overline{PRE}	A or B	3.5	5.5	7.7	6.5	2.5	4.2	6.1	ns

operating characteristics, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$	$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$	UNIT	
			TYP	TYP		
C_{pd}	Power dissipation capacitance	Outputs enabled	$C_L = 50$ pF, $f = 10$ MHz	60	60	pF
		Outputs disabled				

timing diagram



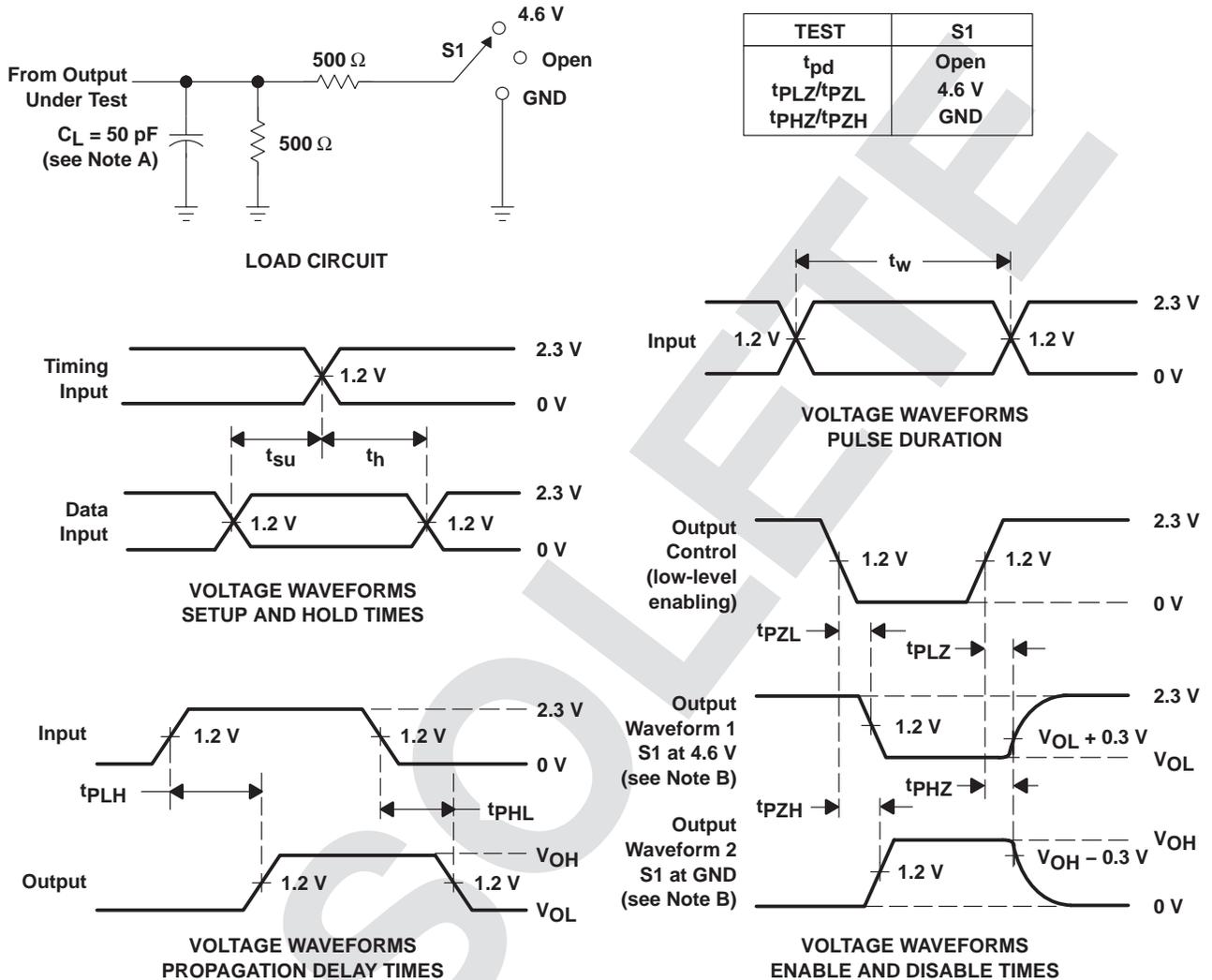
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PARAMETER MEASUREMENT INFORMATION

$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



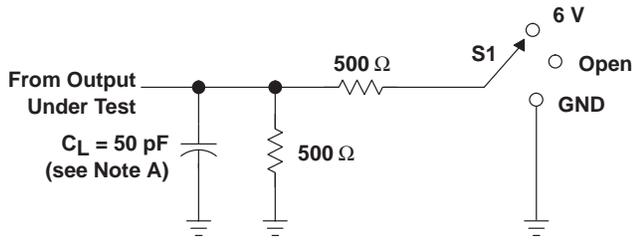
- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

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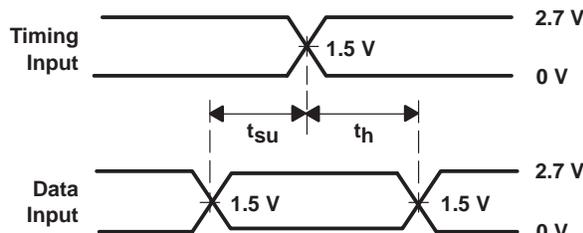
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PARAMETER MEASUREMENT INFORMATION
 $V_{CC} = 2.7\text{ V AND } 3.3\text{ V} \pm 0.3\text{ V}$

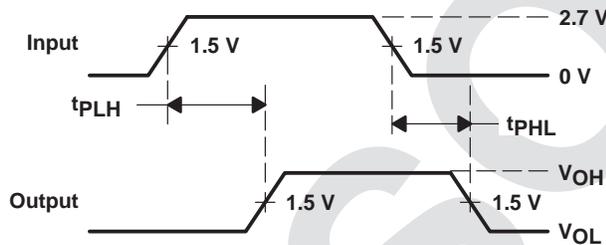


LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



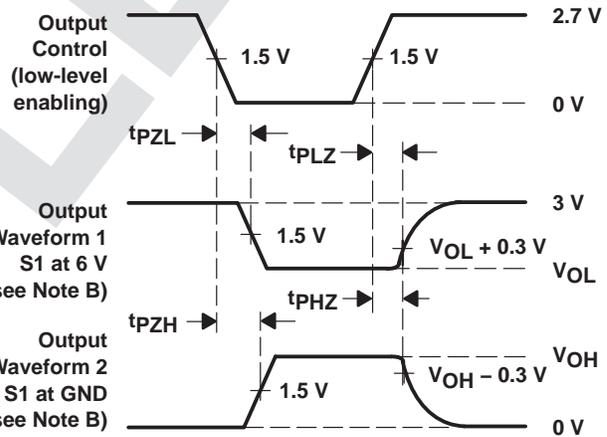
VOLTAGE WAVEFORMS SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS PULSE DURATION



VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 2.5\text{ ns}$, $t_f \leq 2.5\text{ ns}$.
 D. The outputs are measured one at a time with one transition per measurement.
 E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 F. t_{PZL} and t_{PZH} are the same as t_{en} .
 G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ALVC16409DL	OBSOLETE	SSOP	DL	56		TBD	Call TI	Call TI
SN74ALVC16409DLR	OBSOLETE	SSOP	DL	56		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

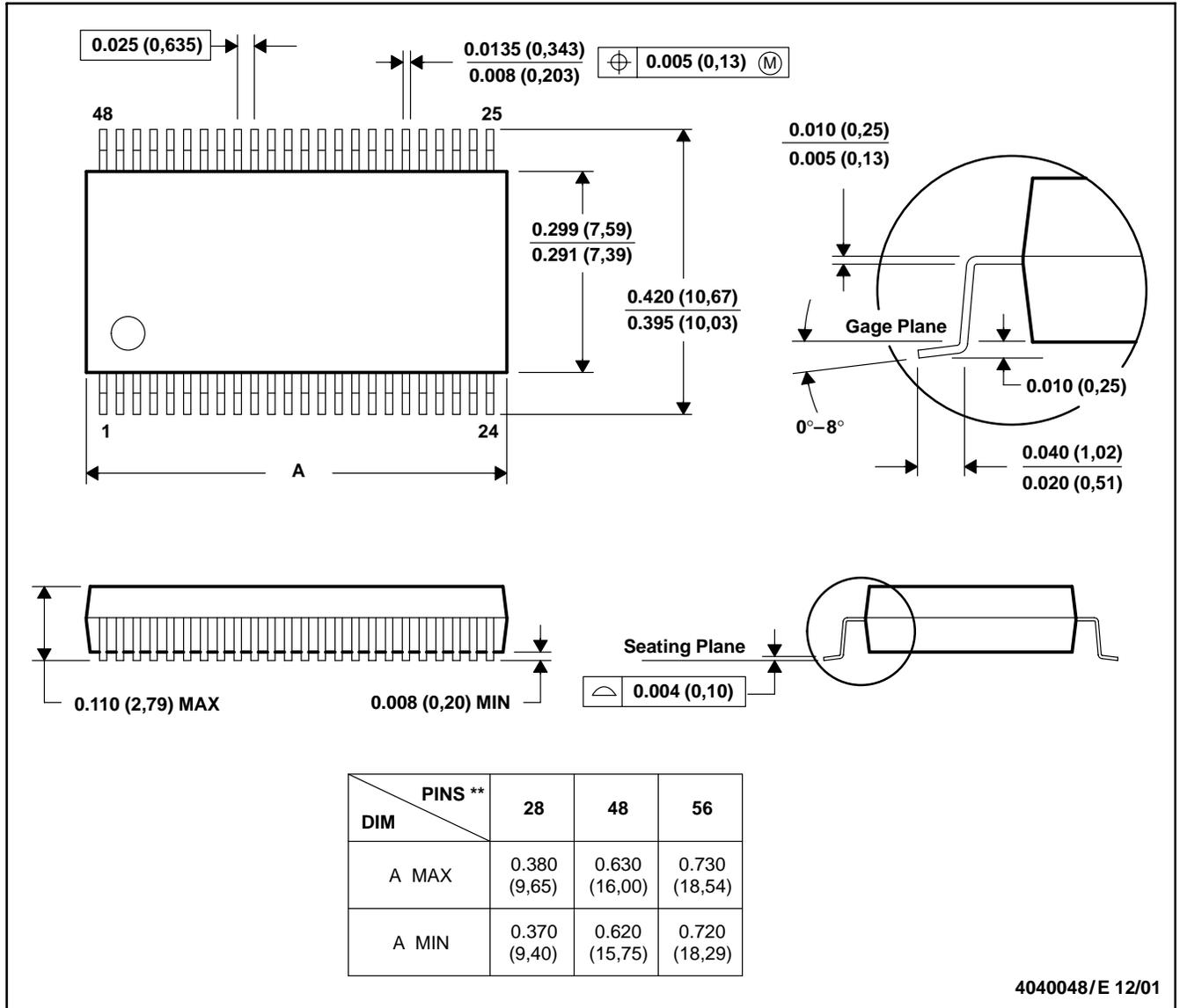
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DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MO-118

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